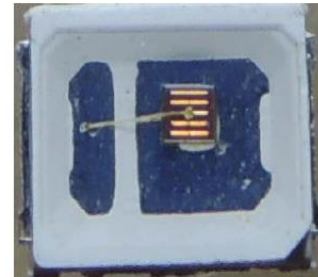


SE-SMD2835-660R5

2835 SMD 660nm Rot

✧ **Features:**

- 2.8mm×3.5mm SMT LED, 0.83mm thickness
- PLCC-2 package
- White package
- Suitable for all SMT assembly and solder process
- Available on tape and reel



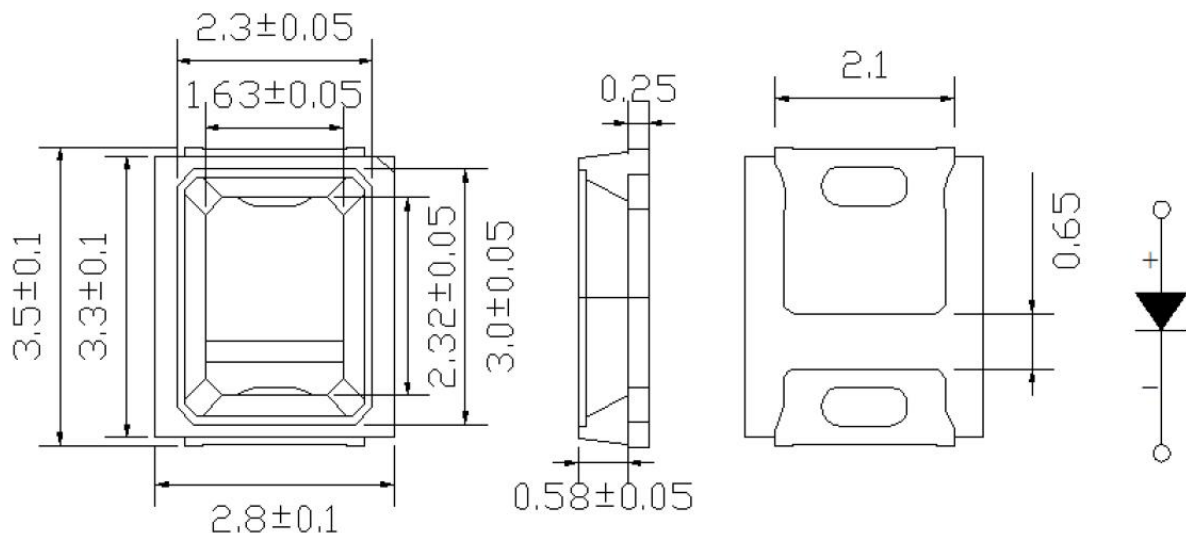
✧ **Description**

The Red source color devices are made with AlGaInP on sapphire Light Emitting Diode.

✧ **Application**

- Optical indicator
- Indicator and backlighting in telephone and fax
- Flat backlight for LCD, switch and symbol
- Light pipe application
- General use

✧ **Package Dimensions**



**NOTES:**

1. All dimensions are in millimeter[unit];
2. Tolerance is±0.1mm(0.004") especially other specified;
3. Specifications are subject to change without notice.

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Part No.	Emitted Color	Len's Color	Chip Material
SE-SMD2835-660R5	Red	Water clear	AlGaInP

✧ **Absolute Maximum Ratings(Ta=25°C)**

Item	Symbol	Maximum	Unit
Power Dissipation	PD	500	mW
Continuous Forward Current	I <sub>Fmax</sub>	150	mA
Peak Forward Current(1/10 Duty Cycle 0.1ms Pulse Width)	I <sub>FP</sub>	200	mA
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature Range	T <sub>opr</sub>	-40 to+85	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to+100	°C

✧ **Electrical/Optical Characteristics(Ta=25°C)**

Item	Symbol	Condition	Min.	Typ.	Max	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =150mA	1.8	2.1	2.6	V
Luminous Flux	I <sub>o</sub>	I <sub>F</sub> =150mA	2	3	4	lm
Wavelength	$\lambda_d$	I <sub>F</sub> =150mA	640	645	650	nm
Peak Wavelength	$\lambda_p$	I <sub>F</sub> =150mA	660	663	665	nm
Viewing Angle	2 $\theta_{1/2}$	I <sub>F</sub> =150mA	--	120	--	Deg
Capacitance	C	V <sub>F</sub> =0V, f=1MHZ	--	110	--	pF
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	--	5	10	uA

✧ Typical Electro-Optical Characteristics Curves

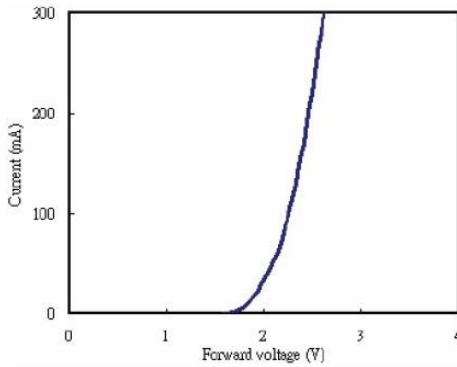


Fig.1 The I-V characteristics (0-300mA)

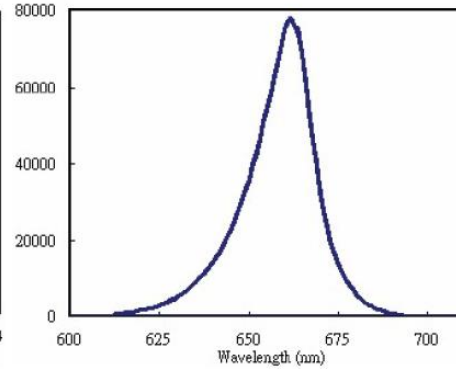


Fig.2 The EL spectrum

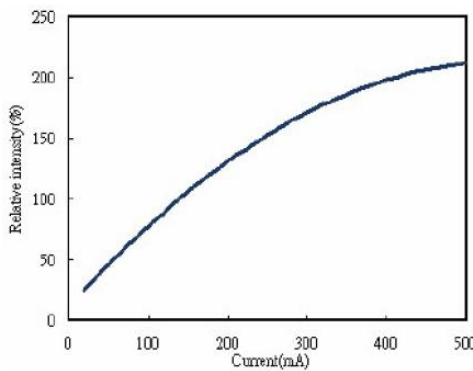


Fig.3 Relative intensity vs forward current

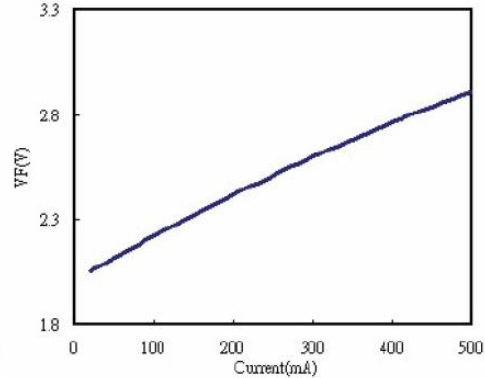


Fig.4 The V-I characteristics (0-500mA)

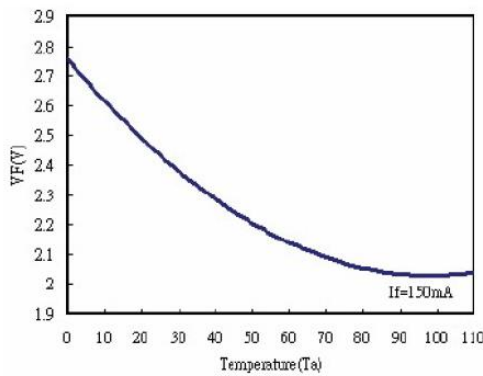


Fig.9 The forward voltage vs Ta(°C)

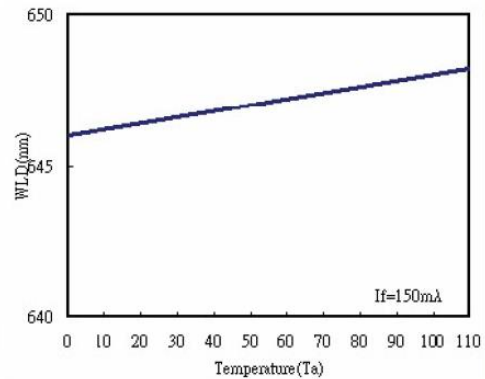


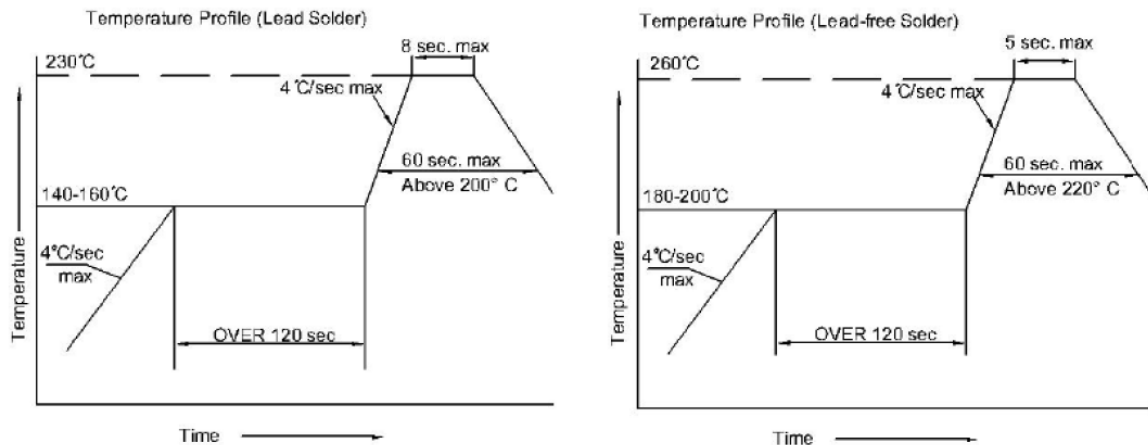
Fig.10 The WLD shift vs Ta(°C)

❖ **Reliability Test Items And Conditions**

NO.	Item	Test Condition	Test Hr/cycle/time	Sample Q'ty	Ac/Re
1	Reflow	TEMP:260±5 °C; Min.5Sec	6 min	22pcs	0/1
2	Temperature Cycle	H:+100°C 15mins To(5mins) L:-40°C 15mins	300 cycles	22pcs	0/1
3	Thermal Shock	H:+100°C 15mins To(5mins) L:-40°C 15mins	300 cycles	22pcs	0/1
4	High Temperature Storage	TEMP:+260°C	1000hrs	22pcs	0/1
5	Low Temperature Storage	TEMP:-40°C	1000hrs	22pcs	0/1
6	DC Operating Life	IF=20MA	1000hrs	22pcs	0/1
7	High Temperature	85°C	1000hrs	22pcs	0/1
8	High Humidity	85%R.H.	1000hrs	22pcs	0/1

❖ **SMT Reflow Soldering Instructions**

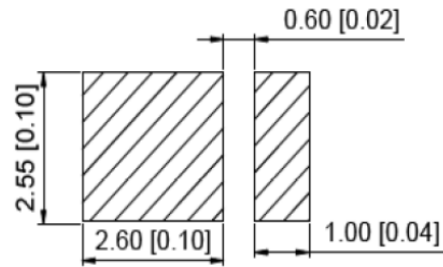
Number of reflow process shall be than 2 times and cooling  
Process to normal temperature is required between first and second  
soldering process



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◇ Recommended Soldering Pad Dimensions



◇ Tape Specification: 3,000PCS per reel

